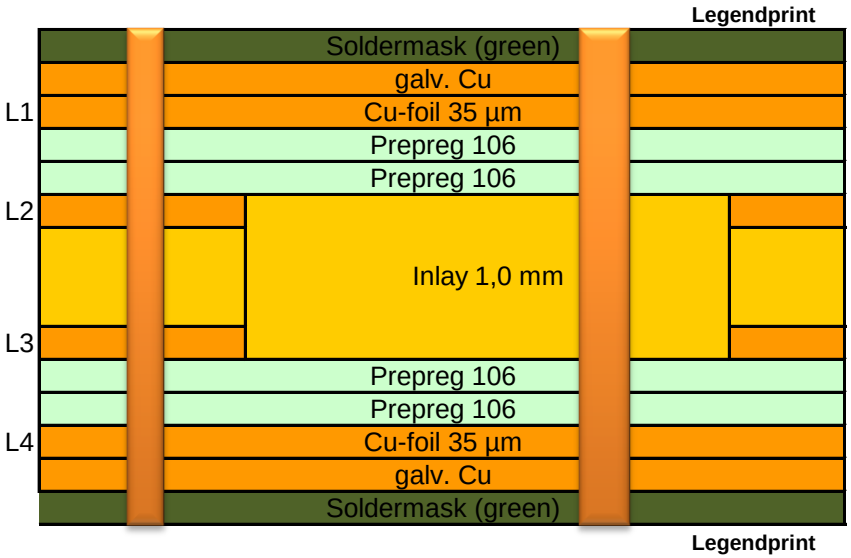
Infineon Inlay-LP

030681*



	Thickness nominal in µm	Thickness empirical in µm
Legendprint		
Soldermask (green)	20	30
galv. Cu	25	43
L1 Cu-foil 35 µm	35	32
Prepreg 106	50	50
Prepreg 106	50	50
L2	35	32
Inlay 1,0 mm	930	930
L3	35	32
Prepreg 106	50	50
Prepreg 106	50	50
L4 Cu-foil 35 µm	35	32
galv. Cu	25	43
Soldermask (green)	20	30
Legendprint		
	1360	1404

Thickness after lamination, without galv. Cu, without soldermask in mm	1,26	±10%

Total thickness in mm	1,40	±10%

SCHWEIZER ELECTRONIC		TVP o.k.
BMA	030681-001 / Zg.-Nr.: 02 / 26.10.2018	